

Y-5225/ Y-5225P

High Tg, Lead-Free and very low loss Laminate & Prepreg

产品特点

- 无卤，高玻璃化转变温度 (Tg:180°C)
- 低 DK、低 DF
- DK/DF 环境稳定性好
- 低 Z 轴膨胀系数和通孔可靠性
- 适应无铅工艺制程

应用领域

服务器、储存、路由器、基架、基站等

Key Features:

- Halogen-free, High Tg (Tg:180°C)
- Lower DK and low DF
- Stable DK/DF with different environment
- Low Z-CTE and excellent through hole reliability
- Compatible with lead-free process

Applications

Server/Storage, Routers, Backplane, Base station. etc

General Properties

Property	Item	IPC-TM-650	Test Condition	Units	Typical value
	玻璃化转变温度 Glass Transition Temperature	2.4.25	DSC	°C	180
	X,Y 轴方向膨胀系数 X,Y-CTE	2.4.24.5	TMA	ppm/°C	12~14
	Z 轴方向膨胀系数 Z axis-CTE	2.4.24	TMA, Before TG	ppm/°C	42
			TMA, After TG	ppm/°C	230
			50~260°C	%	2.7
			T288	min	≧60
			T300	min	≧60
	288°C 热冲击 Thermal stress	2.6.8	288°C, solder dip	S	Pass
热失重(weight loss 5%) Decomposition temperature	2.4.24.6	TGA	°C	385	
电性能 Electrical	体积电阻 Volume Resistivity	2.5.17.1	C-96/35/90	MΩ-cm	>10 ⁸
	表面电阻 Surface Resistivity	2.5.17.1	C-96/35/90	MΩ	>10 ⁸
	耐电弧 Arc Resistance	2.5.1	A	S	120
	击穿电压 Dielectric Breakdown	2.5.6	A	KV	40

	电气强度 Electric Strength(thickness<0.5mm)	2.5.6.2	A		KV/mm	40
	介电常数 Permittivity (RC54%)	2.5.5.13	1GHz		/	3.9
			5GHz		/	3.9
			10GHz		/	3.8
	介电损耗 Loss Tangent (RC54%)	2.5.5.13	1GHz		/	0.0060
			5GHz		/	0.0075
10GHz			/	0.0080		
物理性能 Physical	弯曲强度 Flexural Strength	2.4.4	A	LW	MPa	480
				CW		410
	剥离强度 Peel Strength (1oz LP)	2.4.8	288°C/10s		lb/inch	5.0
	阻燃等级 Flammability	UL94	UL94		/	V-0
	吸水率 Moisture Absorption	2.6.2.1	D-24/23		%	0.09

Specimen thickness: 0.4mm or 0.8mm.

Test Method is according to IPC TM-650 or National Standard Test Method.

The data above is only for reference, and the actual data will have deviation, according to varieties of test equipment and method.